



IBIS Open Forum Minutes

Meeting Date: **November 19, 2021**

Meeting Location: **Teleconference**

VOTING MEMBERS AND 2021 PARTICIPANTS

Analog Devices (Maxim Integrated)	Tushar Pandey*, Pawan Sai, Yan Liang, Glenn Amparo*, Jermaine Lim*, Rolynd Aquino* Curtis Clark*, Wei-Hsing Huang, Miyo Kawata (Fred Balistreri) (Yunong Gan)
ANSYS	Zhen Mu*, Ryo Sato, Takuya Moriya, Tadaaki Yoshimura, Morihiro Nakazato, Masahiro Nakahara, Yitong Wen (Sophia Feng)
Applied Simulation Technology	(Stephen Searce), Guobing Han
Broadcom	Stefan Paret, David Duque, Longfei Bai (Guohua Wang)
Cadence Design Systems	Zhiping Yang*, Songping Wu
Celestica	Hang (Paul) Yan, Kai Zhao, Liqing Guang, Peng Xiao, Wei Gao, Hai Wen, Xiaojun Zhou, Xusheng Liu, Xing Wang, Zhang Hui (Christian Sporrer)
Cisco Systems	(Abdelgader Abdalla)
Dassault Systemes (CST)	Hsinho Wu*, Michael Mirmak*
Ericsson	Radek Biernacki*, Fangyi Rao, Pegah Alavi, Todd Bermensolo, Majid Ahadi Dolatsara*, Xiuguo Jiang, Jiarui Wu
Google	Toshinori Kageura, Yoshio Akashi, Satoshi Nakamizo
Huawei Technologies	David Banas
Infineon Technologies AG	Steven Parker*
Instituto de Telecomunicações	Mike LaBonte*, Walter Katz
Intel Corporation	Randy Wolff*, Justin Butterfield, Aniello Viscardi, Akshay Shivaji Chaudhari, Dragos Dimitriu, Chunqiang Weng, Hongyan Li, Tree Li, Zhang Cheng
Keysight Technologies	Masayuki Honda, Mikio Sugawara
Keysight Technologies Japan K.K.	Chulsoon Hwang, Anfeng Huang, Yifan Ding, Ling Zhang
Luminous Computing	Jon Burnett
Marvell	(John Baprawski)
MathWorks (SiSoft)	Arpad Muranyi*, Weston Beal*
Micron Technology	Franz Pflieger, Sebastien Kollinger
Micron Memory Japan, G.K.	Kunimoto Mashino
MST EMC Lab	(Gerard Mas)
NXP	Ted Mido*, Andy Tai, Claire Cao, Jinghua Huang, Kevin Li, Xuefeng Chen, Yuyang Wang, Zhishuan Ye
SerDesDesign.com	
Siemens EDA (Mentor)	
Siemens AG	
Siemens Electronic Design Automation	
Japan K.K.	
STMicroelectronics	
Synopsys	

Teraspeed Labs
Xilinx
ZTE Corporation

Zuken
Zuken USA
Zuken Japan

Bob Ross*
(Romi Mayder)
Bowen Shen, Changgang Yin, Dongdong Ye,
Liqiang Meng, Xiaoxuan Liu, Hongbin Shi,
Jian Huang, Jinlong Li
Michael Schäder, Chithrupa Ramesh
Lance Wang*
Kensuke Yoshijima, Shiratori Takayuki

OTHER PARTICIPANTS IN 2021

A&D Print Engineering Co., Ltd.
Achronix Semiconductor
AET, Inc.
Alibaba, Inc.
AMD Japan
Analog Devices
Apollo Giken Co., Ltd.
ATE Service Corporation
Aurora System Inc.
AVL Software and Functions
Blue Ocean Smart System
Canon Components Inc.
Canon Inc.
Ciena
CMK Corporation
Continental Automotive
Cybernet Systems Co., Ltd.
D-Clue Technologies Co., Ltd.
De Montfort University (IEEE EMC)
Denso Corporation
Elite Material Co.
Empyrean
Eswin
Extreme Networks
Faurecia Clarion Electronics Co., Ltd.
Fujifilm Manufacturing Co., Ltd.
Fujitsu Interconnect Technologies Limited
Fujitsu Limited

Fujitsu Optical Components Limited
Fujitsu Interconnect Technologies Limited,
Japan
Fulhan
Furukawa Electric Co., Ltd.
H3C
Hamamatsu Photonics K.K.
Hamburg University of Technology
Harbin Institute of Technology
Hitachi, Ltd.
HOEI Co., Ltd.
Hoya Corporation

Ryu Murota, Minoru Hasegawa
Hansel Dsilva
Keisuke Tqahara
Cassie Yan
Tadashi Arai
Patrick Deroy
Satoshi Endo
Yutaka Honda
Hitoshi Ishikawa
Wolfgang Röhrner
Junyong Deng
Takeshi Nagata
Syouji Matsumoto, Satoru Ishikawa
Taha Kheyar, Kaisheng Hu
Motoshi Nakamura, Masaki Abe
Julnar Musmar, Stefanie Schatt
Shiho Nagae, Takayuki Tsuzura
Kenzo Tan
Alistair Duffy
Koji Ichikawa
Nick Huang
Chenghan Jia, Jiajie Zhao, Yuting Yin, Tao Zhang
Sitao Chen
Robert Haller
Yasui Takatsugu
Rumi Maeda
Manabu Fukuzawa
Takashi Kobayashi, Hideki Takauchi,
Yoshio Nabeyama, Makoto Yoshino
Masaki Kunii
Masaki Kirinaka

Zhengyi Zhu
Takumi Ohuchi
Xinyi Hu, Muwang Ye, Zixiao Yang
Akihiro Inoguchi
Cheng Yang
Gang Zhang
Goro Hamamoto, Keisuke Yamamoto
Tatsuya Chiba
Masayuki Hagiwara

IB-Electronics
Innotech Corporation
Integran Co., Ltd.
Interchip Corporation
IT-Beratung-Maurer
Japan Aviation Electronics Industry
Limited
Japan Radio Co., Ltd.
JEDAT Inc.
JEITA
Jujube LLC
JVC Kenwood Corporation
Kandou Bus
KEI Systems
Keita Smart Mirai Creations Co., Ltd.
Keyence Corporation
Kioxia Corporation

Kioxia Systems Co., Ltd.

Konica Minolta, Inc.
Kyocera Corporation
MD Systems Co., Ltd.
Megachips Corporation
Mercury Systems
Microchip Norway
Mitsubishi Electric Corporation
Mitsubishi Electric Corporation
Mitsumine-Denshi Co., Ltd.
Modech Inc.
Molex Japan LLC
Murata Manufacturing Co., Ltd.
NTT Electronics Cross Technologies
Corporation
Panasonic Corporation

Politecnico di Torino

PWB Corporation
Renesas Electronics Corporation

Ricoh Company, Ltd.

Ricoh Electronic Devices Co., Ltd.
Rohm Co., Ltd.
RTC

Makoto Matsumuro
Shinobu Seki, Tasuku Kanomata
Norio Miyamoto
Satoshi Fujita, Hiroaki Takahashi
Manfred Maurer
Kentaro Toda

Hiroto Katakura, Takashi Sato, Youichi Suzuki
Nobuto Ono
Akihiko Kawasaki, Kyoji Yamazaki, Hisashi Saito
Taiji Hosaka
Yasutoshi Ojima, Hidetoshi Suzuki, Takuo Fujimura
Sherman Chen
Shinichi Maeda
Keita Miyasato
Tomoh Uchida
Masato Kanie, Jyuichiro Noda,
Takaya Yamamoto, Mohamedo Mansuru,
Minori Yoshitomi, Takayuki Mizogami
Jyun Shibasaki, Tomomichi Takahashi,
Yukio Tanoue
Takeshi Nomura
Aki Tanaka
Hidetoshi Ogawa
Tomochika Kitamura
Vincent Tam
Lars Snith
Yusuke Suzuki, Masaki Watanabe
Yasuhiro Segawa
Ryouichi Nakahigashi
Tadashi Akio
Masashi Iwata
Hideki Miyazawa, Seiji Hidaka, Shigeaki Hashimoto
Megumi Nagata

Shinichi Tanimoto, Shingo Enomoto,
Atsushi Nakano
Stefano Grivet-Talocia, Paolo Manfredi,
Alessandro Zanco, Felipe Treviso,
Marco Destefano, Riccardo Trincherro,
Tomasso Bradde
Toru Ohhisa
Kazuyuki Sakata, Masato Suzuki,
Kazuaki Tsuchiyama, Kazunori Yamada,
Jyunichi Yamada, Billy Chen, Mengting Liao
Toshihiko Makino, Hisao Kurosu, Nobuo Nakane,
Miyoko Goto
Takeshi Hara
Nobuya Sumiyoshi, Kenichi Ozaki
Ken Whigham

SAXA, Inc.
Schneider Electric Japan Holdings Ltd.
Seiko Epson Corporation
Sihi Semiconductor
Shimadzu Corporation
Silvaco Japan Co., Ltd
Simberian
Socionext Inc.

Sohwa & Sophia Technologies
Sony Global Manufacturing & Operations Corporation
 Sony LSI Design Inc.
 Sony Semiconductor Manufacturing Corporation
Technopro Design Company
Teikyo Heisei University
Tektronix & Fluke Corporation
Tektronix Company
Teradyne
Tokyo Drawing Ltd.
Tomen Devices Corporation
Toshiba Corporation
 Toshiba Development & Engineering Corporation
 Toshiba Electronic Devices & Storage Corporation
University of Illinois, Urbana
WADOW
Xpedic

Yamaha Corporation
Yazaki Parts Co., Ltd.
Yokogawa Electric Corporation

Takayuki Ito, Takayuki Sato
Hiroaki Fujita
Toshiyuki Nishiyama
Ying He
Kazuo Nakajima
Yoshihiko Yamamoto
Yuriy Shlepnev
Shizue Kato, Hajime Ohmi, Motoaki Atsumura,
Megumi Ohno, Ayako Kitamoto
Tomoki Yamada
Yuichi Ikeya, Atsushi Yoshimoto

Kazuki Murata, Toru Fujii
Kengo Imazato

Mai Fukuoka
Kohtaro Hachiya
Katsuhiko Suzuki
Takafumi Watanabe
Tao Wang, Tomoh Tashiro
Masahiko Nakamura
Kinji Mitani
Yasuki Torigishi
Nobuyuki Kasai, Nobuhiro Tsuruta

Atsushi Tomishima, Toshihiro Tsujimura,
Yoshinori Fukuba
Jose Shutt-Ainé, Xinying Wang
Kazuhiko Kusunoki
Bing Sun, Chengzhi Hu, Huashan Cui, Max Cang,
Qiujie Zhang, Ruijie Zhao, Sophia Gui, Wei He,
Yiwei Yang, Yunbing Xia, Zhouxiang (Zachary) Su,
Wenliang Dai, Yan Liu
Hiroyuki Kai, Tetsuya Kakimoto
Kenichi Fujisawa
Daisuke Kamezawa

In the list above, attendees at the meeting are indicated by *. Those submitting an email ballot for their member organization for a scheduled vote are indicated by ^. Principal members or other active members who have not attended are in parentheses. Participants who no longer are in the organization are in square brackets.

UPCOMING MEETINGS

The connection information for future IBIS teleconferences is as follows:

Microsoft Teams meeting

Join on your computer or mobile app

[Click here to join the meeting](#)

Join with a video conferencing device

106010980@teams.bjn.vc

Video Conference ID: 114 666 897 5

[Alternate VTC dialing instructions](#)

Or call in (audio only)

[+1 267-768-8015,554664847#](tel:+12677688015554664847#) United States, Philadelphia

Phone Conference ID: 554 664 847#

[Find a local number](#) | [Reset PIN](#)

[Learn More](#) | [Meeting options](#)

All teleconference meetings are 8:00 a.m. to 9:55 a.m. US Pacific Time. Meeting agendas are typically distributed seven days before each Open Forum. Minutes are typically distributed within seven days of the corresponding meeting.

NOTE: "AR" = Action Required.

INTRODUCTIONS AND MEETING QUORUM

Glenn Amparo introduced himself as a system application manager at Analog Devices, mainly handling IBIS models. Jermaine Lim said she was Glenn's manager. She created IBIS models for ADI parts. Rolynd Aquino said he was creating IBIS-AMI models for ADI parts. Mike LaBonte declared that a quorum had been reached.

CALL FOR PATENTS

Randy Wolff called for declaration of any patents or pending patents related to the IBIS, IBIS-ISS, ICM, or Touchstone 2.0 specifications. No patents were declared.

REVIEW OF MINUTES AND ARS

Randy Wolff called for comments on the minutes of the October 29, 2021, IBIS Open Forum teleconference. Lance Wang moved to approve the minutes. Radek Biernacki seconded the motion. There were no objections.

Randy reviewed ARs from the previous meeting.

- Michael Mirmak to inform JEITA "LPB" group about upcoming IBIS 7.1 version [AR]
Michael said (later in the meeting) this was done.
- Randy Wolff (and Steve Parker) to update BIRD215 status on the website [AR]
Randy said this was done.
- Bob Ross to update status of BUG225 on website [AR]
Bob said this was done.
- Bob Ross to update status of BUG226 on website [AR]
Bob said this was done.

ANNOUNCEMENTS, CALL FOR ADDITIONAL AGENDA ITEMS

None.

MEMBERSHIP STATUS AND TREASURER'S REPORT

Bob Ross reported that a \$900 prepayment for 2022 dues had been received. Membership status was unchanged, with 29 members. Analog Devices (ADI) had acquired Maxim Integrated, so representatives from either could cast votes. Bob asked to receive the ADI logo with permission to use it for our web page. A full payment of \$17,500.00 for ibischk7 version 7.1.0 was expected to be made by the end of the year.

WEBSITE ADMINISTRATION

Steven Parker reported that posted minutes were up to date, along with other changes. A home page banner for the latest IBIS 7.1 draft document had been added. Randy Wolff said the Japan and China summits could be moved to the bottom of the events page.

MAILING LIST ADMINISTRATION

Curtis Clark reported that everything was operating normally. There had been a few new subscribers. Bob Ross said we needed to ensure that subscriptions using mentor.com and sisoft.com email addresses were resubscribed using new addresses if service for the current ones would be ending soon. Mike LaBonte said he had done that, and Curtis had made changes for Walter Katz.

LIBRARY UPDATE

Zhiping Yang reported that there had been no contacts about the library page. Work on the GitHub model website had continued. Randy Wolff said he could put some example models there, with the new EMD keywords. Zhiping invited all to consider contributing models. The email address to reach Zhiping would be found on the Models page at <https://ibis.org/models/>.

INTERNATIONAL/EXTERNAL ACTIVITIES

- Conferences

Randy Wolff said we might begin discussing DesignCon, to be held in April of next year. Bob Ross asked how close the IEEE EMC+SIPI conference would be to that. The IEEE SPI conference would be closer to DesignCon. Bob suggested penciling in dates for possible summits. Randy Wolff to suggest dates for 3 potential 2022 summits [AR].

- Press Updates

None.

- Related standards

IEC 63055/IEEE 2401, JEITA "LPB"

Michael Mirmak reported that his AR had been completed, he had informed the JEITA LPB group about the upcoming IBIS 7.1 version release. He would let us know when a response from the JEITA LBP group was received. IEEE DASC and JEITA had held a joint meeting the previous night, but Michael could not attend. He would report once the meeting notes were issued.

SUMMIT PLANNING AND REVIEW

- Virtual Asian IBIS Summit (Japan), Friday, November 12, 2021, 08:30 to 12:00 JST
- Virtual Asian IBIS Summit (China), Friday, November 19, 2021, 09:00 to 13:00 CST

Randy said both summit meetings had been recorded, and links for the recordings would be working soon. Individual Japan presentations already had video links. There had been more than 130 Japan attendees. He said there was interest in an updated IBIS Cookbook, covering new features since IBIS 4.2. Randy felt we might be able to issue smaller cookbooks, not a large, comprehensive one. These would be listed as training materials on the website. Mike LaBonte and Randy said it was good to see the interest in moving IBIS forward. Bob Ross said there were about 64 attendees in the China summit.

Randy said he had been contacted by Informa Markets about the prospect for a summit co-located with DesignCon next year. The conference will be held April 5 to 7, Tuesday to Thursday. We would need to decide whether to meet in person. Randy would check on room availability and cost for either Monday or Friday [AR]. Randy said we could conduct a preference survey, but that need not be done immediately. Hsinho Wu said DesignCon would be held at the Santa Clara Convention Center next year. Bob Ross asked if DesignCon would have a combination of onsite and virtual presentations. Hsinho said no. Bob said travel restrictions might make a hybrid summit a good choice. He said that the quoted room and meals cost had been quite high for 2020. Randy was open to hybrid meeting logistics. Tushar Pandey said it would be good to have both options.

QUALITY TASK GROUP

Mike LaBonte said the group meets on Tuesdays at 9:00 a.m. PT. The group continues to oversee the next ibischk release, ibischk7.1.0. Details would be discussed later in the meeting.

Weston Beal asked if the IBIS Quality Checklist would be updated. Mike said there were no plans, suggesting that Weston might join the task group meeting to discuss that.

The Quality task group checklist and other documentation can be found at:

http://www.ibis.org/quality_wip/

ADVANCED TECHNOLOGY MODELING TASK GROUP

Arpad Muranyi reported that the group meets on Tuesdays at 12:00 a.m. PT. The group had decided that no new major discussions should be started until IBIS 7.1 was finalized. The group was suspending the next three meetings. Meetings would resume Jan 4, 2022. Upon resumption, PAMn would be discussed, along with Power Supply Induced Jitter (PSIJ), and GDDR6X issues. Randy Wolff said the IBIS-AMI repeater reference flow BIRD draft needed some updates. Arpad hoped to have IBIS 7.1 approved soon, so that existing BIRDs and drafts could be adjusted to be relative to IBIS 7.1, for IBIS 7.2 consideration.

Task group material can be found at:

http://www.ibis.org/macromodel_wip/

INTERCONNECT TASK GROUP

Michael Mirmak reported that the Interconnect task group remained suspended. Its former time slot was being used by the Editorial task group.

Task group material can be found at:

http://www.ibis.org/interconnect_wip/

EDITORIAL TASK GROUP

Michael Mirmak reported that the group had continued meeting on Wednesdays at 8:00 a.m. PT. He thanked Randy Wolff for organizing the most recent meeting. Michael said draft 20 of IBIS 7.1 would be released to the group that day. He thanked all who had reviewed the drafts, noting that some potential conflicts had been found. Michael added that IBIS 7.1 would contain a total of 103 keywords.

Task group material can be found at:

http://www.ibis.org/editorial_wip/

NEW ADMINISTRATIVE ISSUES

None

BIRD211.3: IBIS AMI REFERENCE FLOW IMPROVEMENTS

Discussion was tabled.

BIRD213: EXTENDING IBIS-AMI FOR PAM_n ANALYSIS

Discussion was tabled.

BIRD166.4: RESOLVING PROBLEMS WITH REDRIVER INIT FLOW

Discussion was tabled.

BIRD181.1: I-V TABLE CLARIFICATIONS

Discussion was tabled.

BIRD190: CLARIFICATION FOR REDRIVER FLOW

Discussion was tabled.

BIRD210: NEW REDRIVER AMI FLOW

Discussion was tabled.

REVIEW OF IBIS 7.1 DRAFT

Randy Wolff shared the draft and noted that it was draft 19, whereas draft 20 would be available soon. He described a [C Comp Model] terminal line issue that had been found. It was intended that no two [C Comp Model] terminals could have the same terminal type, but that had not been stated. Michael Mirmak showed the new sentence, which would appear on page 86 in draft 20.

Randy said a sentence had also been removed. Michael showed the deleted sentence, which stated that A_gnd was not required under File_TS or File_IBIS-ISS. Randy said the same line appeared in other areas such as EMD. Bob Ross clarified that a terminal type could appear

zero or one times. Michael said draft 20 would also contain minor indentation and italicization changes.

Arpad Muranyi asked if there would be any changes to the voting schedule. Randy said it was not felt that a new BIRD was needed for the draft 20 changes. He said draft 20 would be posted as the final draft, and the December 10 vote date would be kept. Mike LaBonte and Michael Mirmak felt that that was consistent with previous practice.

Arpad moved to schedule a vote to approve the IBIS 7.1 draft. Michael seconded. Arpad added that people should continue reviewing. Randy said minor fixes could be incorporated into the upcoming motion to vote. Without objection, the motion was approved. Randy Wolff to send email ballot for IBIS 7.1 approval [AR].

Radek Biernacki asked for the latest draft link to be sent. Arpad said it would, once the draft was final.

IBISCHK AND TSCHK PARSER AND BUG STATUS

Bob Ross said the IBISCHK developer had found an error, and there would be a few more changes. He thanked those who had reviewed the source code and tested the executables. A new bug had been found, for something that had previously worked correctly. Bob had checked all the new QA tests. Randy Wolff said a minor issue had been found with IBIS-ISS subcircuit file lookup for EMD models. Bob said this would be the first time the parser would be available at the same time as the specification. Bob felt having the parser work happening at the same time as specification finalization had also helped produce a better specification.

Bob said we would need to accept the parser source code to authorize the payment. Randy said the Quality group had discussed holding an Open Forum acclamation vote to allow payment to be made potentially before the next Open Forum meeting.

Mike LaBonte moved to authorize the IBIS Quality Task Group to decide acceptance of the final source code for IBISCHK7.1.0, allowing the developer to be paid upon acceptance. Radek Biernacki seconded. Without objection the motion passed.

Arpad Muranyi asked if a roll call vote was required to approve the payment. Mike said that vote had already been held and passed. The new vote would be only to accept the final work of the developer, allowing payment to be made. He believed that previous acceptance votes had been by acclamation.

NEW TECHNICAL ISSUES

None

NEXT MEETING

The next IBIS Open Forum teleconference meeting would be held on December 10, 2021. The following teleconference meeting was tentatively scheduled for January 7, 2022.

Michael Mirmak moved to adjourn. Arpad Muranyi seconded the motion. The meeting adjourned.

=====

NOTES

IBIS CHAIR: Randy Wolff (208) 363-1764

rrwolff@micron.com

Principal Engineer, Silicon SI Group, Micron Technology, Inc.
8000 S. Federal Way
P.O. Box 6, Mail Stop: 01-720
Boise, ID 83707-0006

VICE CHAIR: Lance Wang (978) 633-3388

lance.wang@ibis.org

Solutions Architect, Zuken USA
238 Littleton Road, Suite 100
Westford, MA 01886

SECRETARY: Mike LaBonte

mlabonte@mathworks.com

Senior Engineer
1 Lakeside Campus Drive
Natick, MA 01760

TREASURER: Bob Ross (503) 246-8048

bob@teraspeedlabs.com

Engineer, Teraspeed Labs
10238 SW Lancaster Road
Portland, OR 97219

LIBRARIAN: Zhiping Yang (650) 214-0868

zhipingyang@google.com

Sr. Hardware Manager, Google LLC
1600 Amphitheatre Parkway
Mountain View, CA 94043

WEBMASTER: Steven Parker (845) 372-3294

sparker@marvell.com

Senior Staff Engineer, DSP, Marvell
2070 Route 52
Hopewell Junction, NY 12533-3507

POSTMASTER: Curtis Clark

curtis.clark@ansys.com

ANSYS, Inc.
150 Baker Ave Ext
Concord, MA 01742

This meeting was conducted in accordance with SAE ITC guidelines.

All inquiries may be sent to info@ibis.org. Examples of inquiries are:

- To obtain general information about IBIS.
- To ask specific questions for individual response.
- To subscribe to or unsubscribe from the official ibis@freelists.org and/or ibis-users@freelists.org email lists (formerly ibis@eda.org and ibis-users@eda.org):
 - <https://www.freelists.org/list/ibis>

- <https://www.freelists.org/list/ibis-users>
- To subscribe to or unsubscribe from one of the task group email lists: ibis-macro@freelists.org, ibis-interconn@freelists.org, ibis-editorial@freelists.org, or ibis-quality@freelists.org:
 - <https://www.freelists.org/list/ibis-macro>
 - <https://www.freelists.org/list/ibis-interconn>
 - <https://www.freelists.org/list/ibis-editorial>
 - <https://www.freelists.org/list/ibis-quality>
- To inquire about joining the IBIS Open Forum as a voting Member.
- To purchase a license for the IBIS parser source code.
- To report bugs or request enhancements to the free software tools: ibischk6, tschk2, icmchk1, s2ibis, s2ibis2 and s2iplt.

The BUG Report Form for ibischk resides along with reported BUGs at:

<http://www.ibis.org/bugs/ibischk/>
<http://www.ibis.org/bugs/ibischk/bugform.txt>

The BUG Report Form for tschk2 resides along with reported BUGs at:

<http://www.ibis.org/bugs/tschk/>
<http://www.ibis.org/bugs/tschk/bugform.txt>

The BUG Report Form for icmchk resides along with reported BUGs at:

<http://www.ibis.org/bugs/icmchk/>
http://www.ibis.org/bugs/icmchk/icm_bugform.txt

To report s2ibis, s2ibis2 and s2iplt bugs, use the Bug Report Forms which reside at:

<http://www.ibis.org/bugs/s2ibis/bugs2i.txt>
<http://www.ibis.org/bugs/s2ibis2/bugs2i2.txt>
<http://www.ibis.org/bugs/s2iplt/bugspl.txt>

Information on IBIS technical contents, IBIS participants and actual IBIS models are available on the IBIS Home page:

<http://www.ibis.org/>

Check the IBIS file directory on ibis.org for more information on previous discussions and results:

<http://www.ibis.org/directory.html>

Other trademarks, brands and names are the property of their respective owners.

SAE STANDARDS BALLOT VOTING STATUS

Organization	Interest Category	Standards Ballot Voting Status	October 29,	(Summit)	(Summit)	November
			2021	November 12, 2021	November 19, 2021	19, 2021
Analog Devices (Maxim Integrated)	Producer	Inactive	X	-	-	X
ANSYS	User	Inactive	X	-	-	X
Applied Simulation Technology	User	Inactive	-	-	-	-
Broadcom Ltd.	Producer	Inactive	-	-	-	-
Cadence Design Systems	User	Active	X	X	X	X
Celestica	User	Inactive	-	-	-	-
Cisco Systems	User	Inactive	-	-	X	-
Dassault Systemes	User	Inactive	-	-	-	-
Ericsson	Producer	Inactive	-	-	-	-
Google	User	Inactive	X	-	-	X
Huawei Technologies	Producer	Inactive	-	-	X	-
Infineon Technologies AG	Producer	Inactive	-	-	-	-
Instituto de Telecomunicações	User	Inactive	-	-	-	-
Intel Corp.	Producer	Inactive	X	-	-	X
Keysight Technologies	User	Active	-	X	X	X
Luminous Computing	General Interest	Inactive	-	-	-	-
Marvell	Producer	Inactive	X	-	-	X
MathWorks (SiSoft)	User	Active	X	X	X	X
Micron Technology	Producer	Active	X	X	X	X
MST EMC Lab	User	Inactive	-	-	X	-
NXP	Producer	Inactive	-	-	-	-
SerDesDesign.com	User	Inactive	-	-	-	-
Siemens EDA (Mentor)	User	Active	X	X	-	X
STMicroelectronics	Producer	Inactive	-	-	-	-
Synopsys	User	Active	X	X	X	X
Teraspeed Labs	General Interest	Active	X	X	X	X
Xilinx	Producer	Inactive	-	-	-	-
ZTE Corp.	User	Inactive	-	-	X	-
Zuken	User	Active	X	X	X	X

Criteria for SAE member in good standing:

- Must attend two consecutive meetings to establish voting membership
- Membership dues current
- Must not miss two consecutive meetings (voting by email counts as attendance)

Interest categories associated with SAE standards ballot voting are:

- Users - members that utilize electronic equipment to provide services to an end user.
- Producers - members that supply electronic equipment.
- General Interest - members are neither producers nor users. This category includes, but is not limited to, government, regulatory agencies (state and federal), researchers, other organizations and associations, and/or consumers.